

Electronic Patent Application Fee Transmittal

Application Number:	10623788
Filing Date:	21-Jul-2003
Title of Invention:	Strained semiconductor by full wafer bonding
First Named Inventor/Applicant Name:	Leonard Forbes
Filer:	Robert Madden/Lisa Posorske
Attorney Docket Number:	1303.109US1

Filed as Large Entity

Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1201	2	200	400
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				400